IN THE CLAIMS

Please amend claim 48 and add claims 67-69. The current status of the claims is reflected in the below listing of claims.

1. - 47. (Canceled)

48. (Currently Amended) A method for electroless deposition of a nickel layer with internal compressive stress on a substrate, the method comprising:

contacting the substrate with an electrolyte comprising a nickel metal base salt, a reducing agent, a complexing agent, an accelerator, and a stabilizer to thereby electrolessly deposit the nickel layer with internal compressive stress on the substrate, wherein **the nickel layer with internal compressive stress is** ~~electroless deposition occurs~~ **electrolessly deposited** at a deposition rate of 7 µm/h to 14 µm/h with a throughput of 14 to 22 MTO;

wherein the nickel metal base salt of the electrolyte comprises an anion selected from the group consisting of acetate, formate, nitrate, oxalate, propionate, citrate, ascorbate, and combinations thereof;

wherein the nickel metal base salt is added in an initial concentration of 0.048 mol/L to 0.105 mol/L;

wherein the complexing agent is selected from the group consisting of 2-hydroxypropanoic acid, propanedioic acid, and a combination thereof;

wherein during electroless deposition, the electrolyte is buffered to a self-regulating pH between 4.0 and 5.2;

wherein the stabilizer is a metal salt wherein the metal is selected from the group consisting of lead, bismuth, zinc, tin,

and combinations thereof and the metal salt comprises an anion selected from the group consisting of acetate, formate, nitrate, oxalate, propionate, citrate, ascorbate, and combinations thereof; and

wherein optionally other components selected from the group consisting of phosphorus, additional metals, and finely divided particles are co-deposited.

49. (Previously Presented) The method of claim 48, wherein the nickel metal base salt is nickel acetate.

50. - 51. (Canceled)

52. (Previously Presented) The method of claim 48, wherein a first makeup solution is added to the electrolyte during electroless deposition, wherein the first makeup solution comprises a reducing agent, an accelerator, an alkaline buffer, and a complexing agent selected from the group consisting of 2-hydroxypropanoic acid, propanedioic acid, and a combination thereof.

53. (Previously Presented) The method of claim 52, wherein a second makeup solution is added to the electrolyte while practicing the method, wherein the second makeup comprises an accelerator, a stabilizer, and a complexing agent selected from the group consisting of 2-hydroxypropanoic acid, propanedioic acid, and a combination thereof.

54. - 58. (Canceled)

59. (Previously Presented) The method of claim 48, wherein the reducing agent is sodium hypophosphite.

60. (Canceled)

61. (Previously Presented) The method of claim 48, wherein the complexing agent has a concentration between 70 g/L to 90 g/L.

62. - 65. (Canceled)

66. (Previously Presented) The method of claim 51, wherein the throughput is between 70 g/L nickel and 110 g/L nickel.

67. (New) The method of claim 48 wherein the accelerator is a sulfur-containing heterocyle.

68. (New) The method of claim 48 wherein the internal compressive stress of the nickel layer is between -10 N/mm^2 and -40 N/mm^2 when the electrolyte is buffered to a self-regulating pH between 4.3 and 4.8.

69. (New) The method of claim 48 wherein the internal compressive stress of the nickel layer is between 0 and -15 N/mm^2 when the electrolyte is buffered to a self-regulating pH between 4.6 and 5.2.